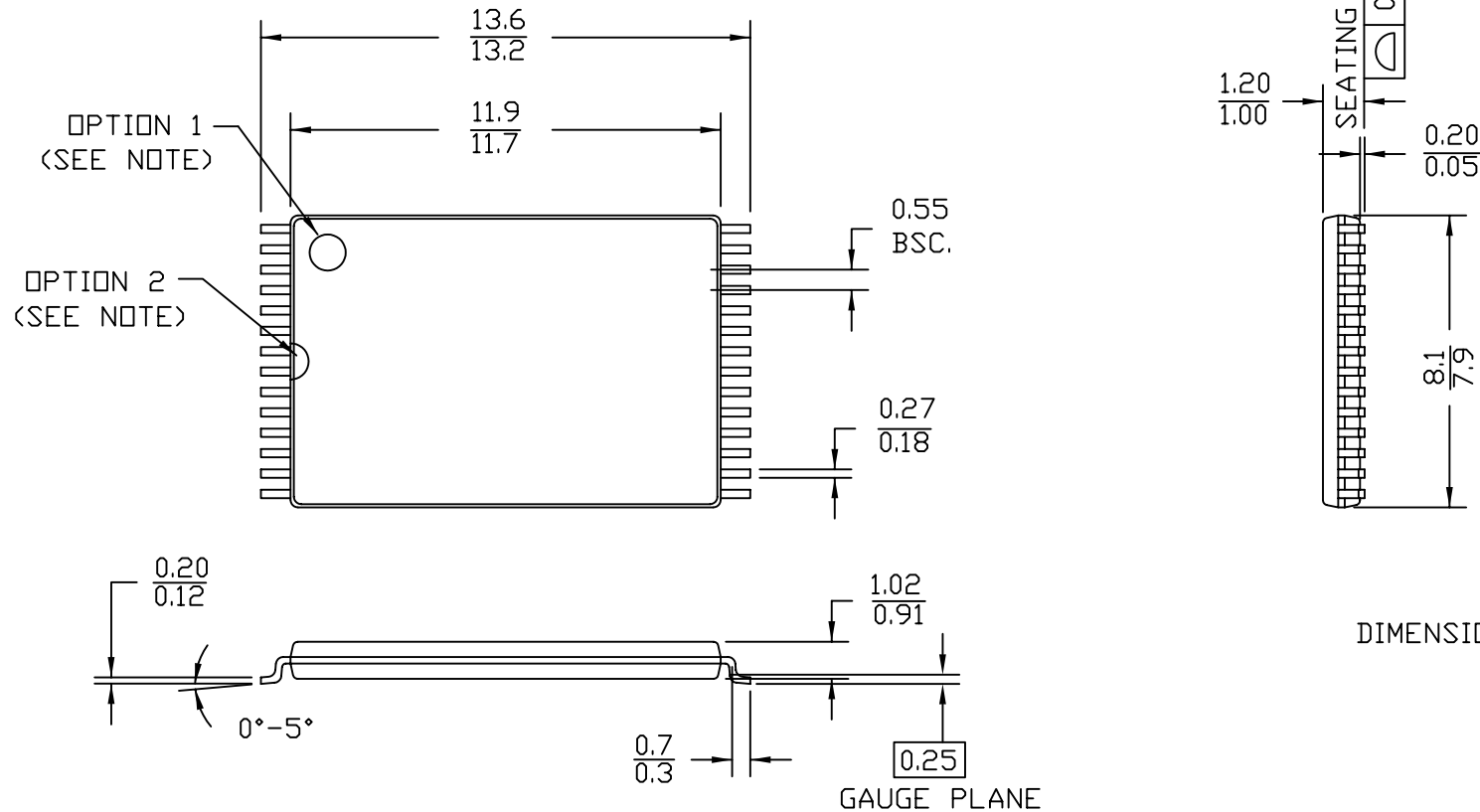


# 28 Lead TSOP I 8 X 13.4mm – STANDARD


NOTE: ORIENTATION I.D MAY BE LOCATED EITHER  
AS SHOWN IN OPTION 1 OR OPTION 2



DIMENSION IN MM  
MAX.  
MIN.

REVISIONS						
PAGE	ZONE	REV	ECN	DESCRIPTION	DATE	APPROVED
1	-	**	1310	NEW RELEASE	08/10/95	N/A
1	-	*A	1590	ADD PIN 1 ID OPTION	05/02/96	N/A
1	-	*B	1604	CHG. LEAD PITCH DIM.	05/16/96	N/A
1	-	*C	1625	ADD PIN COUNT NUMBER	06/10/96	N/A
1	-	*D	46957	CHG. MIN. LEAD THICKNESS DIM.	10/28/96	N/A
1	-	*E	49418	CHG. TITLE/ ADD LEAD COPLANARITY	06/11/97	N/A
1	-	*F	66393	REMOVE THE INCH UNIT ON DIMENSIONS	02/17/00	N/A
1	-	*G	103904	REMOVE PIN NUMBER	11/20/00	N/A
1	-	*H	2835671	Changed template, & title from 28LD (8X13.4) TSOP I PKG OUTL. - STANDARD to PACKAGE OUTLINE, 28LD TSOP I 8X13.4X1.2 MM Z28 (STANDARD)	12/28/09	QAD

THIS DRAWING CONTAINS INFORMATION WHICH IS THE PROPRIETARY PROPERTY OF CYPRESS SEMICONDUCTOR CORPORATION. THIS DRAWING IS RECEIVED IN CONFIDENCE AND ITS CONTENTS MAY NOT BE DISCLOSED WITHOUT WRITTEN CONSENT OF CYPRESS SEMICONDUCTOR CORPORATION.

UNLESS OTHERWISE SPECIFIED ALL DIMENSIONS ARE IN MILLIMETERS STANDARD TOLERANCES ON:  DECIMALS .XX ± 0.05 .XXX ± .XXXX +  MATERIAL N/A  FINISH N/A		DESIGNED BY HTN	DATE 11/20/00	 <b>CYPRESS</b> Company Confidential	
		DRAWN BY HTN	DATE 11/20/00		
		CHECKED BY TSV	DATE 12/28/09		
		APPROVED BY QAD	DATE 12/28/09		
		APPROVED BY JGUA	DATE 12/28/09	TITLE PACKAGE OUTLINE, 28LD TSOP I 8X13.4X1.2 MM Z28 (STANDARD)	
		APPROVED BY N/A	DATE N/A	SIZE A	PART NO. Z28
				DWG NO 51-85071	REV *H
				SCALED TO FIT	N/A
					SHEET 1 OF 1